

■ Block Diagrams

1. S-89430A/89431A Series single operational amplifier (one circuit)

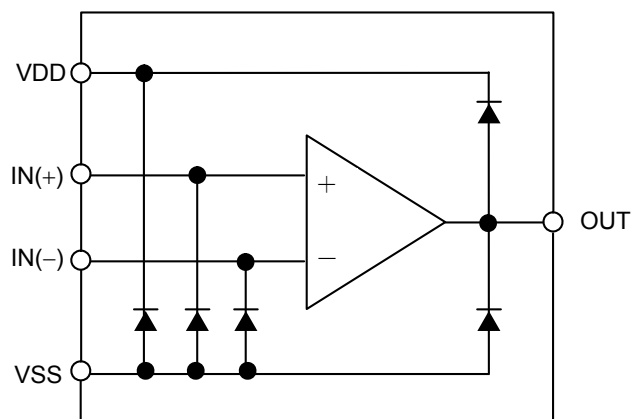


Figure 1

2. S-89430B/89431B Series dual operational amplifier (two circuits)

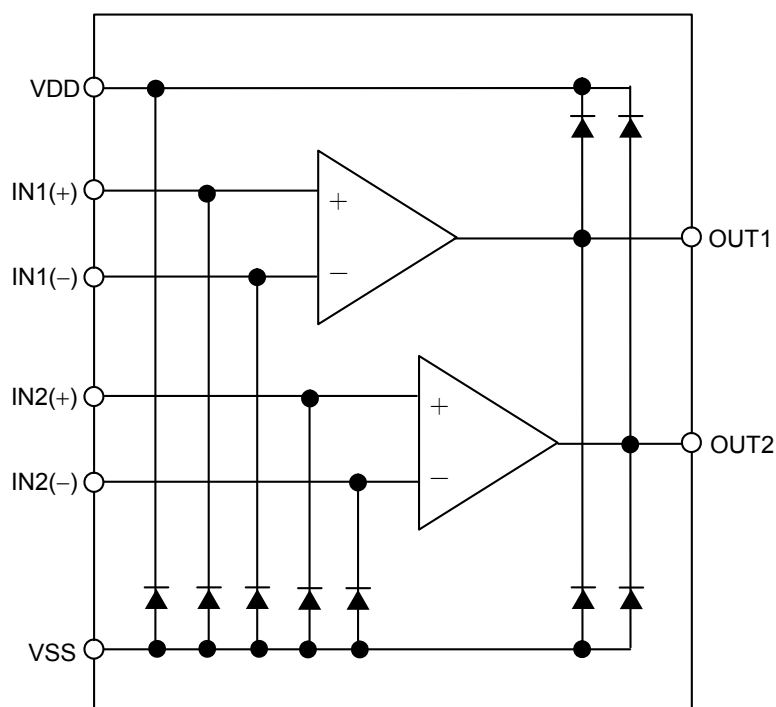


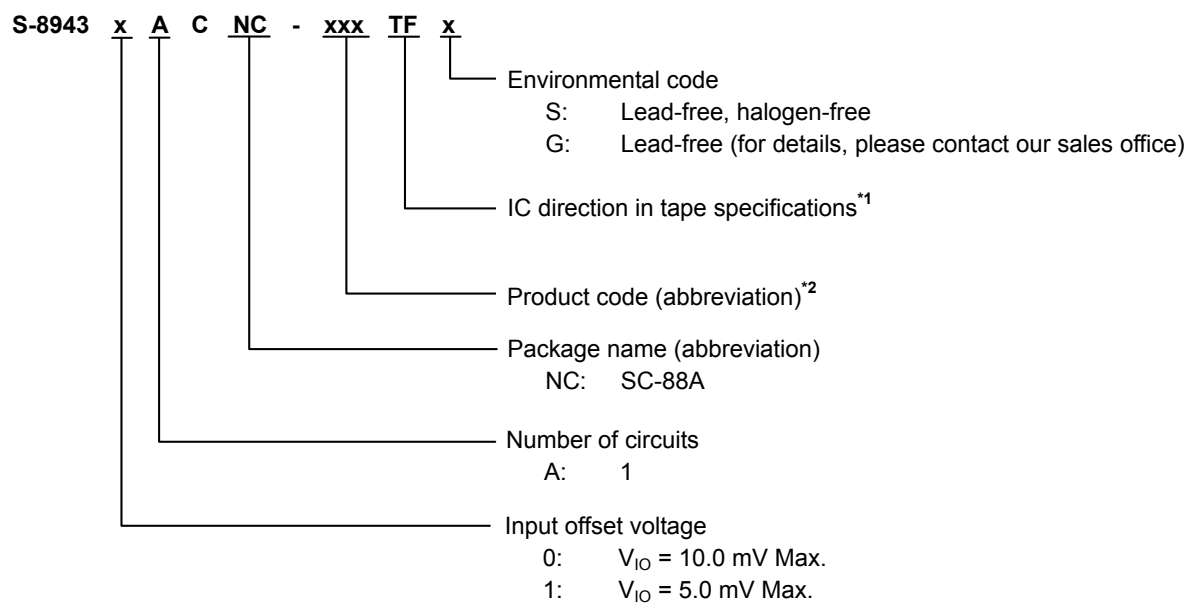
Figure 2

■ Product Name Structure

Users can select the product type for the S-89430/89431 Series. Refer to “1. **Product name**” regarding the contents of product name, “2. **Packages**” regarding the package drawings and “3. **Product name list**” regarding the product type.

1. Product name

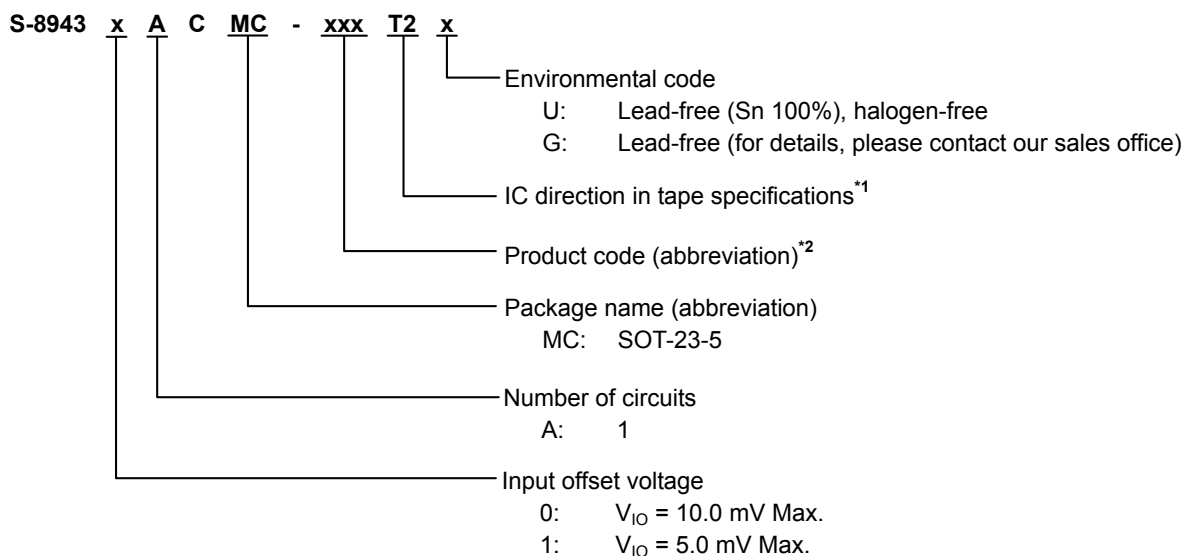
(1) SC-88A



*1. Refer to the tape drawing.

*2. Refer to “3. **Product name list**”.

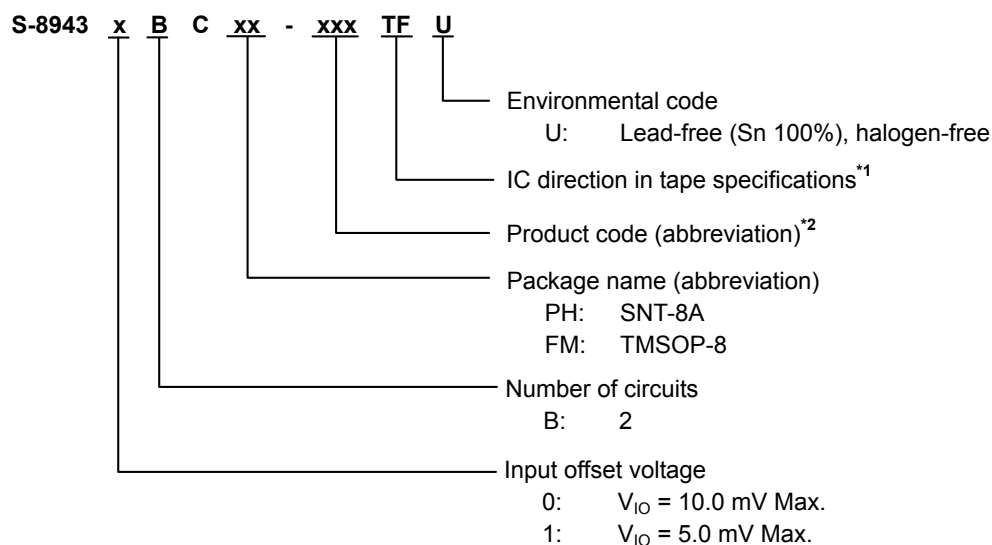
(2) SOT-23-5



^{*1}. Refer to the tape drawing.

^{*2}. Refer to “**3. Product name list**”.

(3) SNT-8A, TMSOP-8



^{*1}. Refer to the tape drawing.

^{*2}. Refer to “**3. Product name list**”.

2. Packages

Package Name	Drawing Code			
	Package	Tape	Reel	Land
SC-88A	NP005-B-P-SD	NP005-B-C-SD	NP005-B-R-SD	–
SOT-23-5	MP005-A-P-SD	MP005-A-C-SD	MP005-A-R-SD	–
SNT-8A	PH008-A-P-SD	PH008-A-C-SD	PH008-A-R-SD	PH008-A-L-SD
TMSOP-8	FM008-A-P-SD	FM008-A-C-SD	FM008-A-R-SD	–

3. Product name list

Table 1

Product name	Input offset voltage	Number of circuits	Package
S-89430ACNC-HBUTFz	10 mV Max.	1	SC-88A
S-89430ACMC-HBUT2x	10 mV Max.	1	SOT-23-5
S-89430BCPH-H4CTFU	10 mV Max.	2	SNT-8A
S-89430BCFM-H4CTFU	10 mV Max.	2	TMSOP-8
S-89431ACNC-HBVTFz	5 mV Max.	1	SC-88A
S-89431ACMC-HBVT2x	5 mV Max.	1	SOT-23-5
S-89431BCPH-H4DTFU	5 mV Max.	2	SNT-8A
S-89431BCFM-H4DTFU	5 mV Max.	2	TMSOP-8

Remark 1. x: G or U

2. z: G or S

3. Please select products of environmental code = U for Sn 100%, halogen-free products.

■ Pin Configurations

1. SC-88A

Top view

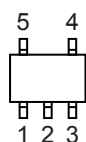


Figure 3

Table 2

(Product with 1 circuit)

Pin No.	Symbol	Description
1	IN(+)	Non-inverted input pin
2	VSS	GND pin
3	IN(-)	Inverted input pin
4	OUT	Output pin
5	VDD	Positive power supply pin

2. SOT-23-5

Top view

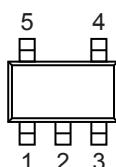


Figure 4

Table 3

(Product with 1 circuit)

Pin No.	Symbol	Description
1	IN(+)	Non-inverted input pin
2	VSS	GND pin
3	IN(-)	Inverted input pin
4	OUT	Output pin
5	VDD	Positive power supply pin

3. SNT-8A

Top view

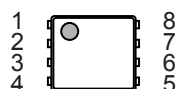


Figure 5

Table 4

(Product with 2 circuits)

Pin No.	Symbol	Description
1	OUT1	Output pin 1
2	IN1(-)	Inverted input pin 1
3	IN1(+)	Non-inverted input pin 1
4	VSS	GND pin
5	IN2(+)	Non-inverted input pin 2
6	IN2(-)	Inverted input pin 2
7	OUT2	Output pin 2
8	VDD	Positive power supply pin

4. TMSOP-8

Top view

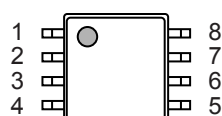


Figure 6

Table 5

(Product with 2 circuits)

Pin No.	Symbol	Description
1	OUT1	Output pin 1
2	IN1(-)	Inverted input pin 1
3	IN1(+)	Non-inverted input pin 1
4	VSS	GND pin
5	IN2(+)	Non-inverted input pin 2
6	IN2(-)	Inverted input pin 2
7	OUT2	Output pin 2
8	VDD	Positive power supply pin

■ Absolute Maximum Ratings

Table 6

(Ta = +25°C unless otherwise specified)

Parameter	Symbol	Absolute Maximum Rating	Unit
Power supply voltage	V_{DD}	$V_{SS} - 0.3$ to $V_{SS} + 7.0$	V
Input voltage	V_{IN}	$V_{SS} - 0.3$ to $V_{SS} + 7.0$ (7.0 Max.)	V
Output voltage	V_{OUT}	$V_{SS} - 0.3$ to $V_{DD} + 0.3$ (7.0 Max.)	V
Differential input voltage	V_{IND}	± 5.5	V
Output pin current	I_{SOURCE}	7.0	mA
	I_{SINK}	7.0	mA
Power dissipation	SC-88A	350 ^{*1}	mW
	SOT-23-5	600 ^{*1}	mW
	SNT-8A	450 ^{*1}	mW
	TMSOP-8	650 ^{*1}	mW
Operating ambient temperature	T_{opr}	-40 to +85	°C
Storage temperature	T_{stg}	-55 to +125	°C

*1. When mounted on board

[Mounted board]

(1) Board size: 114.3 mm \times 76.2 mm \times t1.6 mm

(2) Board name: JEDEC STANDARD51-7

Caution The absolute maximum ratings are rated values exceeding which the product could suffer physical damage. These values must therefore not be exceeded under any conditions.

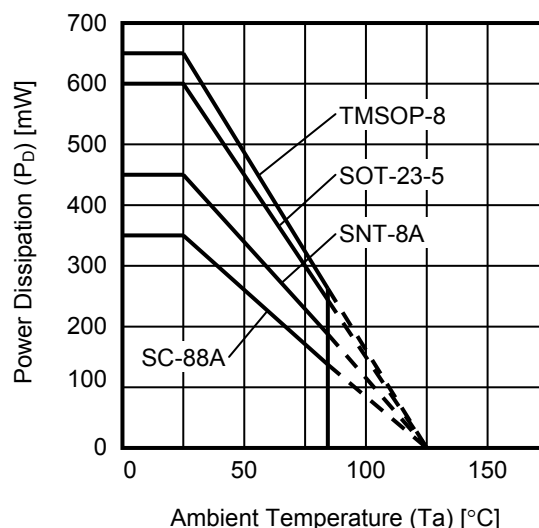


Figure 7 Power Dissipation of Package (When Mounted on Board)

■ Electrical Characteristics

Table 7

(Ta = +25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	Test Circuit
Range of operating power supply voltage	V _{DD}	–	0.9	–	5.5	V	–

1. V_{DD} = 3.0 V

Table 8

DC Electrical Characteristics (V_{DD} = 3.0 V)

(Ta = +25°C unless otherwise specified)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit	Test Circuit
Current consumption (per circuit)*1	I _{DD}	V _{CMR} = V _{OUT} = 1.5 V		–	0.50	0.75	μA	6
Input offset voltage	V _{IO}	V _{CMR} = 1.5 V	S-89430 Series	–10	±5	+10	mV	2
			S-89431 Series	–5	±3	+5	mV	2
Input offset current	I _{IO}	–		–	1	–	pA	–
Input bias current	I _{BIAS}	–		–	1	–	pA	–
Common-mode input voltage range	V _{CMR}	–		0	–	3	V	3
Voltage gain (open loop)	A _{VOL}	V _{SS} + 0.1 V ≤ V _{OUT} ≤ V _{DD} – 0.1 V, V _{CMR} = 1.5 V, R _L = 1.0 MΩ		70	80	–	dB	9
Maximum output swing voltage	V _{OH}	R _L = 100 kΩ		2.95	–	–	V	4
	V _{OL}	R _L = 100 kΩ		–	–	0.05	V	5
Common-mode input signal rejection ratio	CMRR	V _{SS} ≤ V _{CMR} ≤ V _{DD}		45	65	–	dB	3
Power supply voltage rejection ratio	PSRR	V _{DD} = 0.9 V to 5.5 V		70	80	–	dB	1
Source current	I _{SOURCE}	V _{OUT} = V _{DD} – 0.1 V		400	500	–	μA	7
		V _{OUT} = 0 V		4800	6000	–	μA	7
Sink current	I _{SINK}	V _{OUT} = 0.1 V		400	550	–	μA	8
		V _{OUT} = V _{DD}		4800	6000	–	μA	8

- *1. When the output is saturated on the V_{DD} side, a current consumption of up to 3 μ A to 5 μ A may flow.
Refer to “4. Current consumption (per circuit) vs. Common-mode input voltage range characteristics (voltage follower configuration)” in “■ Characteristics (Typical Data)”.

Table 9

AC Electrical Characteristics (V_{DD} = 3.0 V)

(Ta = +25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Slew rate	SR	R _L = 1.0 M Ω , C _L = 15 pF (Refer to Figure 17)	–	5	–	V/ms
Gain-bandwidth product	GBP	C _L = 0 pF	–	4.8	–	kHz
Maximum load capacitance	C _L	–	–	47	–	pF

2. $V_{DD} = 1.8$ V

Table 10

DC Electrical Characteristics ($V_{DD} = 1.8$ V)

($T_a = +25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit	Test Circuit
Current consumption (per circuit)*1	I _{DD}	V _{CMR} = V _{OUT} = 0.9 V		–	0.50	0.75	μA	6
Input offset voltage	V _{IO}	V _{CMR} = 0.9 V	S-89430 Series	–10	±5	+10	mV	2
			S-89431 Series	–5	±3	+5	mV	2
Input offset current	I _{IO}	–		–	1	–	pA	–
Input bias current	I _{BIAS}	–		–	1	–	pA	–
Common-mode input voltage range	V _{CMR}	–		0	–	1.8	V	3
Voltage gain (open loop)	A _{VOL}	V _{SS} + 0.1 V ≤ V _{OUT} ≤ V _{DD} – 0.1 V, V _{CMR} = 0.9 V, R _L = 1.0 MΩ		66	75	–	dB	9
Maximum output swing voltage	V _{OH}	R _L = 100 kΩ		1.75	–	–	V	4
	V _{OL}	R _L = 100 kΩ		–	–	0.05	V	5
Common-mode input signal rejection ratio	CMRR	V _{SS} ≤ V _{CMR} ≤ V _{DD}		35	55	–	dB	3
		V _{SS} ≤ V _{CMR} ≤ V _{DD} – 0.3 V		45	60	–	dB	3
Power supply voltage rejection ratio	PSRR	V _{DD} = 0.9 V to 5.5 V		70	80	–	dB	1
Source current	I _{SOURCE}	V _{OUT} = V _{DD} – 0.1 V		220	300	–	μA	7
		V _{OUT} = 0 V		1200	1800	–	μA	7
Sink current	I _{SINK}	V _{OUT} = 0.1 V		220	300	–	μA	8
		V _{OUT} = V _{DD}		1200	1800	–	μA	8

- *1. When the output is saturated on the V_{DD} side, a current consumption of up to 3 μA to 5 μA may flow.
Refer to “4. Current consumption (per circuit) vs. Common-mode input voltage range characteristics (voltage follower configuration)” in “■ Characteristics (Typical Data)”.

Table 11

AC Electrical Characteristics ($V_{DD} = 1.8$ V)

($T_a = +25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Slew rate	SR	$R_L = 1.0$ M Ω , $C_L = 15$ pF (Refer to Figure 17)	–	4.5	–	V/ms
Gain-bandwidth product	GBP	$C_L = 0$ pF	–	5	–	kHz
Maximum load capacitance	C_L	–	–	47	–	pF

3. $V_{DD} = 0.9$ V

Table 12

DC Electrical Characteristics ($V_{DD} = 0.9$ V)

($T_a = +25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	Test Circuit
Current consumption (per circuit)*1	I _{DD}	V _{CMR} = V _{OUT} = 0.45 V	–	0.50	0.75	μA	6
Input offset voltage	V _{IO}	V _{CMR} = 0.45 V	–10	±5	+10	mV	2
			–5	±3	+5	mV	2
Input offset current	I _{IO}	–	–	1	–	pA	–
Input bias current	I _{BIAS}	–	–	1	–	pA	–
Common-mode input voltage range	V _{CMR}	–	0	–	0.9	V	3
Voltage gain (open loop)	A _{VOL}	V _{SS} + 0.1 V ≤ V _{OUT} ≤ V _{DD} – 0.1 V, V _{CMR} = 0.45 V, R _L = 1.0 MΩ	60	75	–	dB	9
Maximum output swing voltage	V _{OH}	R _L = 100 kΩ	0.85	–	–	V	4
	V _{OL}	R _L = 100 kΩ	–	–	0.05	V	5
Common-mode input signal rejection ratio	CMRR	V _{SS} ≤ V _{CMR} ≤ V _{DD}	25	55	–	dB	3
		V _{SS} ≤ V _{CMR} ≤ V _{DD} – 0.35 V	40	60	–	dB	3
Power supply voltage rejection ratio	PSRR	V _{DD} = 0.9 V to 5.5 V	70	80	–	dB	1
Source current	I _{SOURCE}	V _{OUT} = V _{DD} – 0.1 V	25	65	–	μA	7
		V _{OUT} = 0 V	40	140	–	μA	7
Sink current	I _{SINK}	V _{OUT} = 0.1 V	10	65	–	μA	8
		V _{OUT} = V _{DD}	12	120	–	μA	8

- *1. When the output is saturated on the V_{DD} side, a current consumption of up to 3 μA to 5 μA may flow.
Refer to “4. Current consumption (per circuit) vs. Common-mode input voltage range characteristics (voltage follower configuration)” in “■ Characteristics (Typical Data)”.

Table 13

AC Electrical Characteristics ($V_{DD} = 0.9$ V)

($T_a = +25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Slew rate	SR	$R_L = 1.0$ M Ω , $C_L = 15$ pF (Refer to Figure 17)	–	4	–	V/ms
Gain-bandwidth product	GBP	$C_L = 0$ pF	–	5	–	kHz
Maximum load capacitance	C_L	–	–	47	–	pF

■ Test Circuit (Per Circuit)

1. Power supply voltage rejection ratio

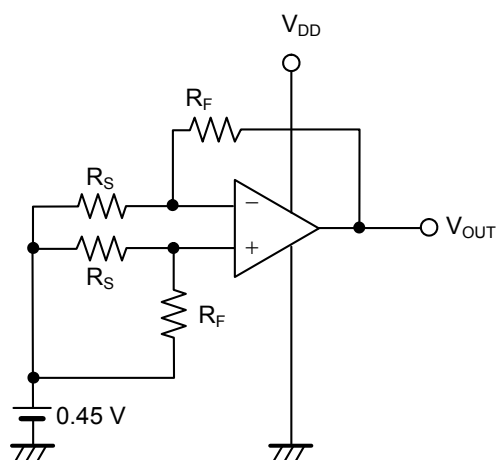


Figure 8

• Power supply voltage rejection ratio (PSRR)

The power supply voltage rejection ratio (PSRR) can be calculated by the following expression, with V_{OUT} measured at each V_{DD} .

Test conditions:

When $V_{DD} = 0.9 \text{ V}$: $V_{DD} = V_{DD1}$, $V_{OUT} = V_{OUT1}$,

When $V_{DD} = 5.5 \text{ V}$: $V_{DD} = V_{DD2}$, $V_{OUT} = V_{OUT2}$

$$\text{PSRR} = 20 \log \left(\left| \frac{V_{DD1} - V_{DD2}}{V_{OUT1} - V_{OUT2}} \right| \times \frac{R_F + R_S}{R_S} \right)$$

2. Input offset voltage

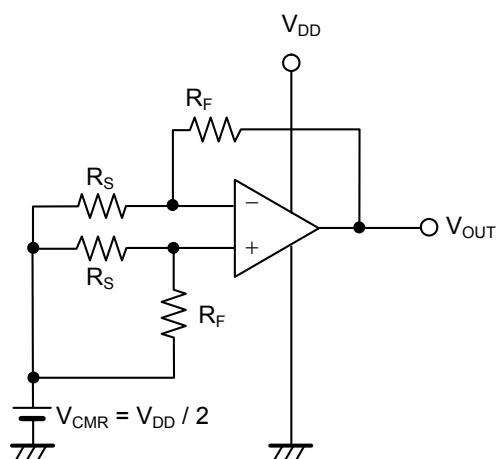


Figure 9

• Input offset voltage (V_{IO})

$$V_{IO} = \left(V_{OUT} - \frac{V_{DD}}{2} \right) \times \frac{R_S}{R_F + R_S}$$

3. Common-mode input signal rejection ratio, common-mode input voltage range

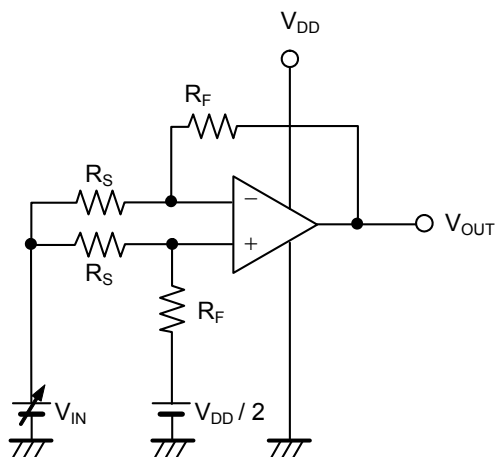


Figure 10

• Common-mode input signal rejection ratio (CMRR)

The common-mode input signal rejection ratio (CMRR) can be calculated by the following expression, with V_{OUT} measured at each V_{IN} .

Test conditions:

When $V_{IN} = V_{CMR\ Max.}$: $V_{IN} = V_{IN1}$, $V_{OUT} = V_{OUT1}$,

When $V_{IN} = V_{CMR\ Min.}$: $V_{IN} = V_{IN2}$, $V_{OUT} = V_{OUT2}$

$$CMRR = 20 \log \left(\left| \frac{V_{IN1} - V_{IN2}}{V_{OUT1} - V_{OUT2}} \right| \times \frac{R_F + R_S}{R_S} \right)$$

• Common-mode input voltage range (V_{CMR})

The common-mode input voltage range is the range of V_{IN} in which V_{OUT} satisfies the common-mode input signal rejection ratio specifications.

4. Maximum output swing voltage (V_{OH})

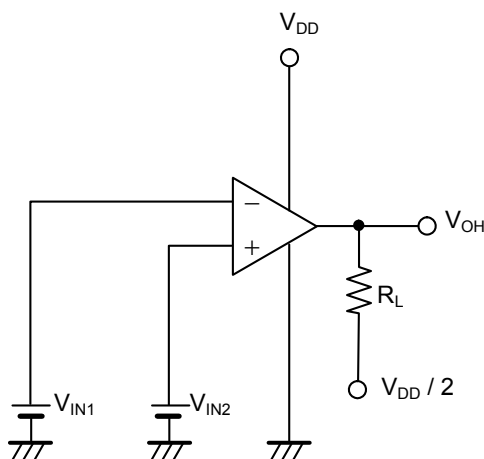


Figure 11

• Maximum output swing voltage (V_{OH})

Test conditions:

$$V_{IN1} = \frac{V_{DD}}{2} - 0.1 \text{ V}$$

$$V_{IN2} = \frac{V_{DD}}{2} + 0.1 \text{ V}$$

$$R_L = 100 \text{ k}\Omega$$

5. Maximum output swing voltage (V_{OL})

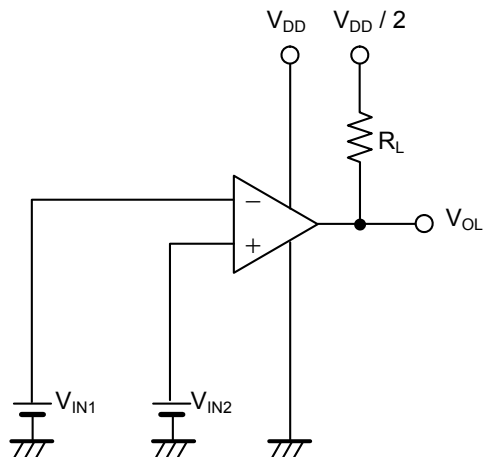


Figure 12

• Maximum output swing voltage (V_{OL})

Test conditions:

$$V_{IN1} = \frac{V_{DD}}{2} + 0.1 \text{ V}$$

$$V_{IN2} = \frac{V_{DD}}{2} - 0.1 \text{ V}$$

$$R_L = 100 \text{ k}\Omega$$

6. Current consumption

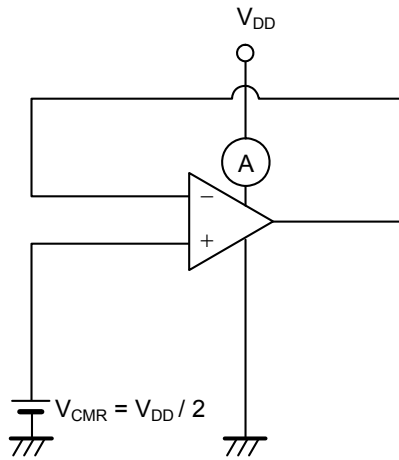


Figure 13

- Current consumption (I_{DD})

7. Source current

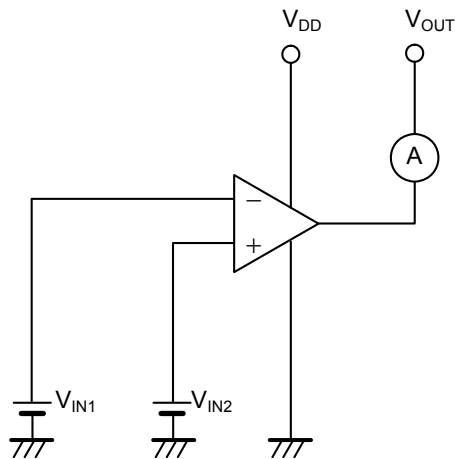


Figure 14

- Source current (I_{SOURCE})

Test conditions:

$$V_{OUT} = V_{DD} - 0.1 \text{ V or } V_{OUT} = 0 \text{ V}$$

$$V_{IN1} = \frac{V_{DD}}{2} - 0.1 \text{ V}$$

$$V_{IN2} = \frac{V_{DD}}{2} + 0.1 \text{ V}$$

8. Sink current

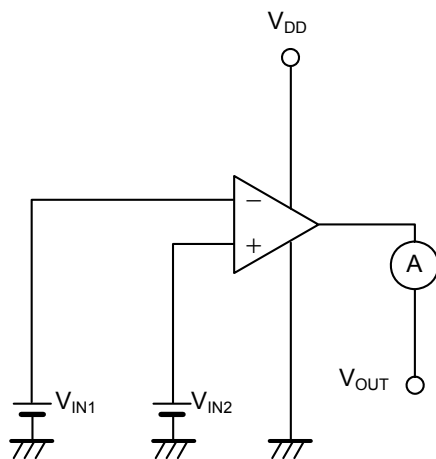


Figure 15

- Sink current (I_{SINK})

Test conditions:

$$V_{OUT} = 0.1 \text{ V or } V_{OUT} = V_{DD}$$

$$V_{IN1} = \frac{V_{DD}}{2} + 0.1 \text{ V}$$

$$V_{IN2} = \frac{V_{DD}}{2} - 0.1 \text{ V}$$

9. Voltage gain (open loop)

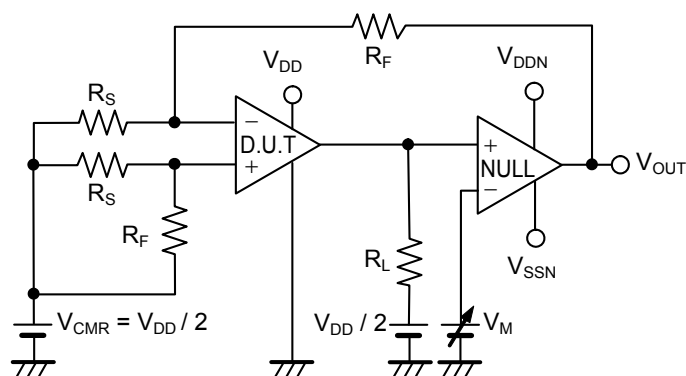


Figure 16

• Voltage gain (open loop) (A_{VOL})

The voltage gain (A_{VOL}) can be calculated by the following expression, with V_{OUT} measured at each V_M .

Test conditions:

When $V_M = V_{DD} - 0.1$ V: $V_M = V_{M1}$, $V_{OUT} = V_{OUT1}$,

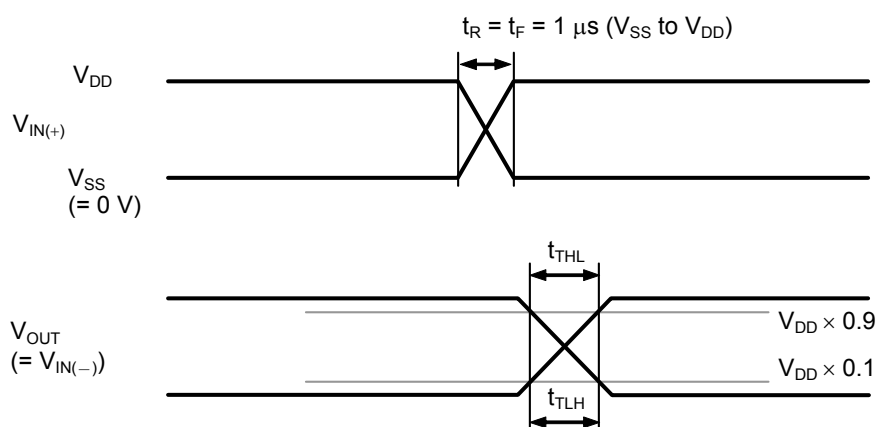
When $V_M = V_{SS} - 0.1$ V: $V_M = V_{M2}$, $V_{OUT} = V_{OUT2}$

$R_L = 1$ M Ω

$$A_{VOL} = 20 \log \left(\left| \frac{V_{M1} - V_{M2}}{V_{OUT1} - V_{OUT2}} \right| \times \frac{R_F + R_S}{R_S} \right)$$

10. Slew rate (SR)

Measured by the voltage follower circuit.



At fall

$$SR = \frac{V_{DD} \times 0.8}{t_{THL}}$$

At rise

$$SR = \frac{V_{DD} \times 0.8}{t_{TLH}}$$

Figure 17

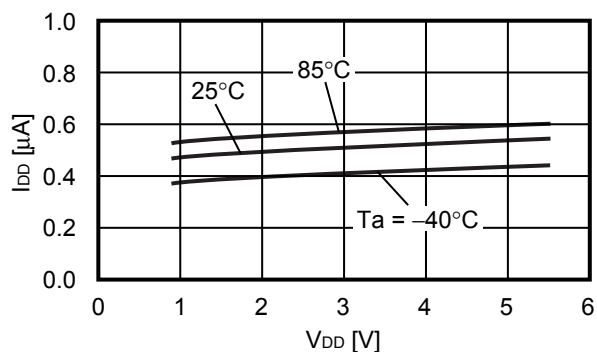
■ Precautions

- When the output is saturated on the V_{DD} side, a current consumption of up to 3 μ A to 5 μ A may flow.
Refer to “4. Current consumption (per circuit) vs. Common-mode input voltage range characteristics (voltage follower configuration)” in “■ Characteristics (Typical Data)”.
- Do not apply an electrostatic discharge to this IC that exceeds performance ratings of the built-in electrostatic protection circuit.
- Use this IC with the output current 7 mA or less.
- ABLIC Inc. claims no responsibility for any disputes arising out of or in connection with any infringement by products including this IC of patents owned by a third party.

■ Characteristics (Typical Data)

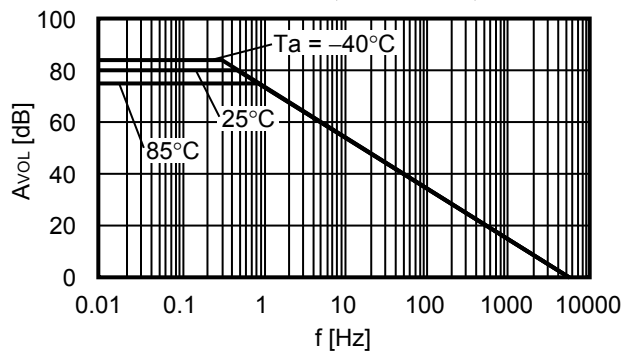
1. Current consumption (per circuit) vs. Power supply voltage

$$I_{DD}-V_{DD}, V_{SS} = 0 \text{ V}, V_{CMR} = V_{OUT} = \frac{V_{DD}}{2}$$

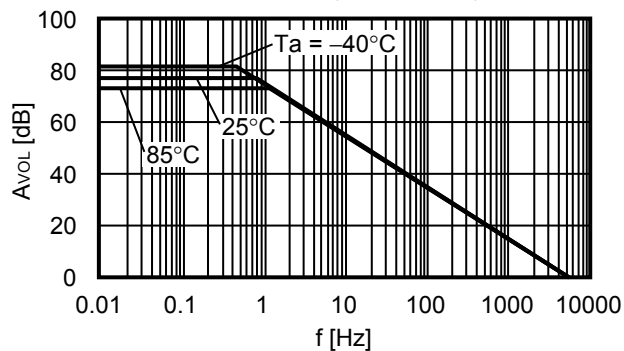


2. Voltage gain vs. Frequency

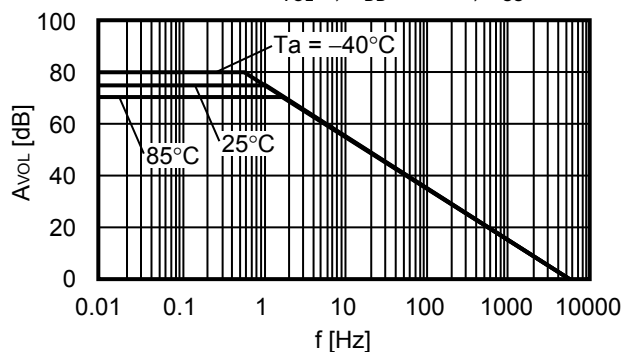
$$A_{VOL}-f, V_{DD} = 3.0 \text{ V}, V_{SS} = 0 \text{ V}$$



$$A_{VOL}-f, V_{DD} = 1.8 \text{ V}, V_{SS} = 0 \text{ V}$$

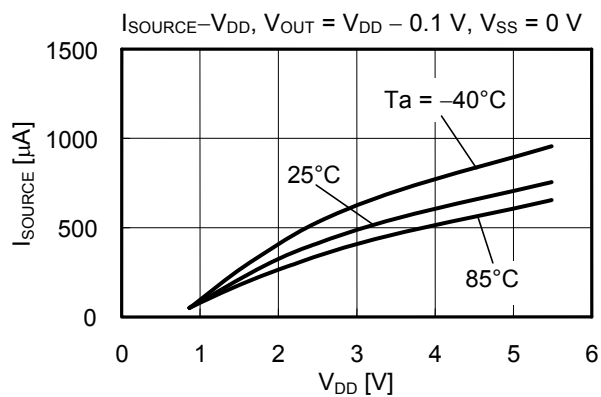


$$A_{VOL}-f, V_{DD} = 0.9 \text{ V}, V_{SS} = 0 \text{ V}$$

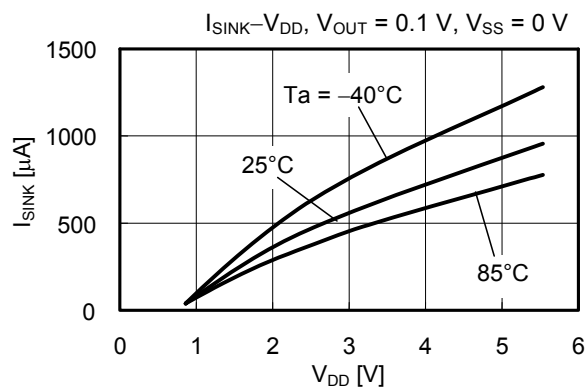


3. Output current

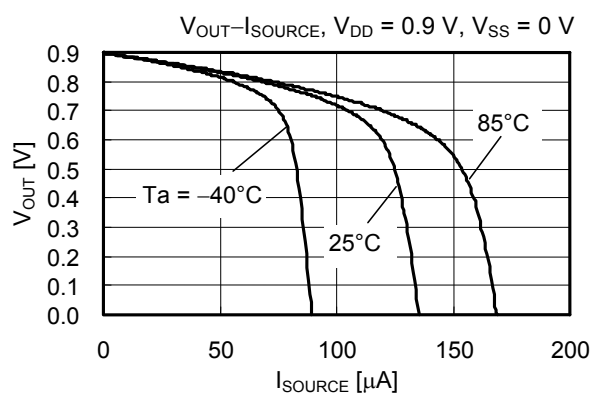
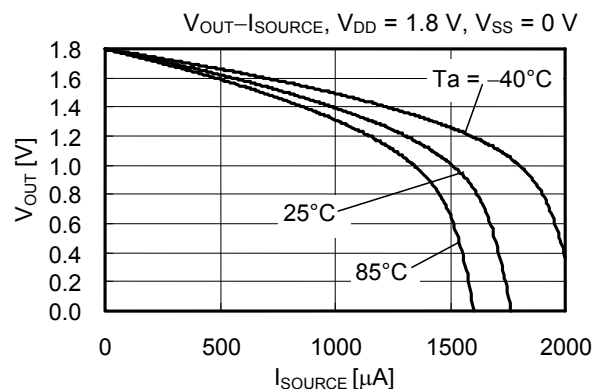
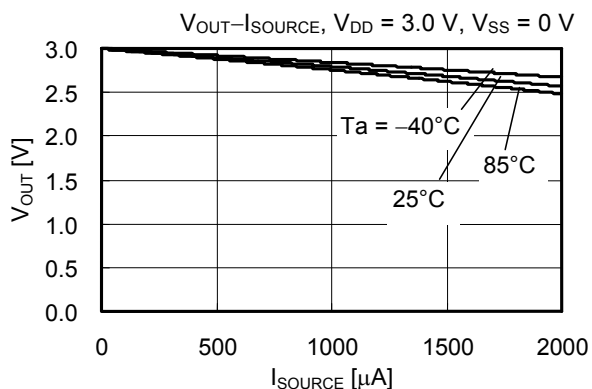
3.1 I_{SOURCE} vs. Power supply voltage



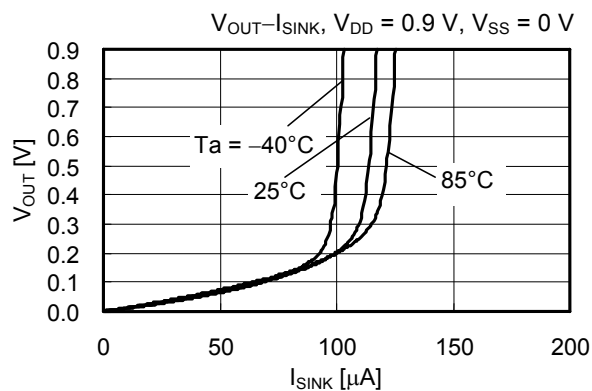
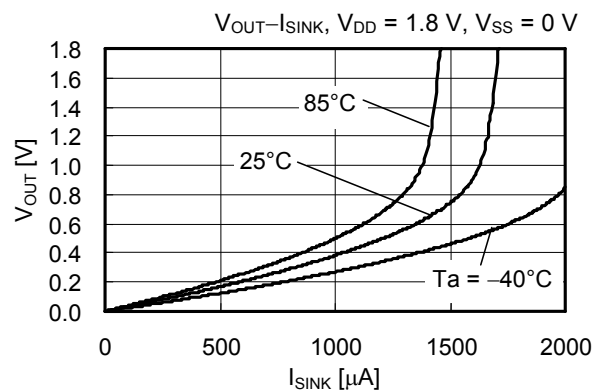
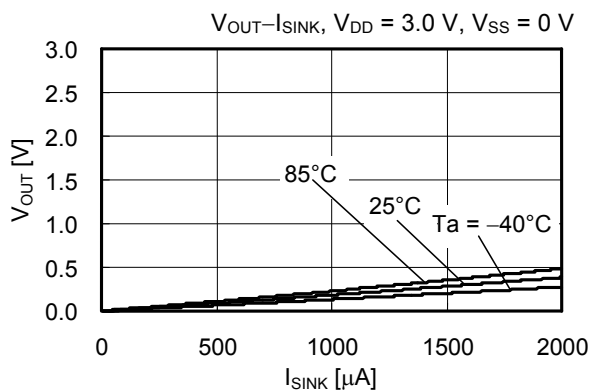
3.2 I_{SINK} vs. Power supply voltage



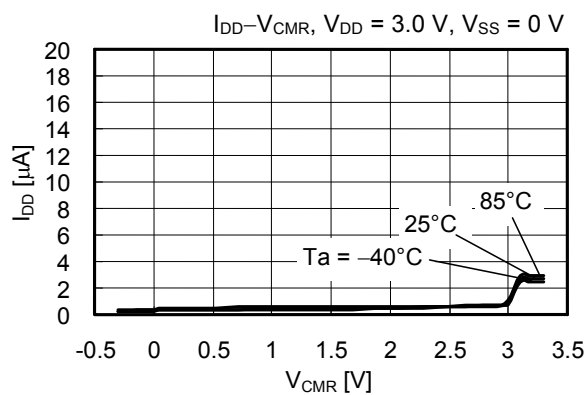
3.3 Output voltage (V_{OUT}) vs. I_{SOURCE}

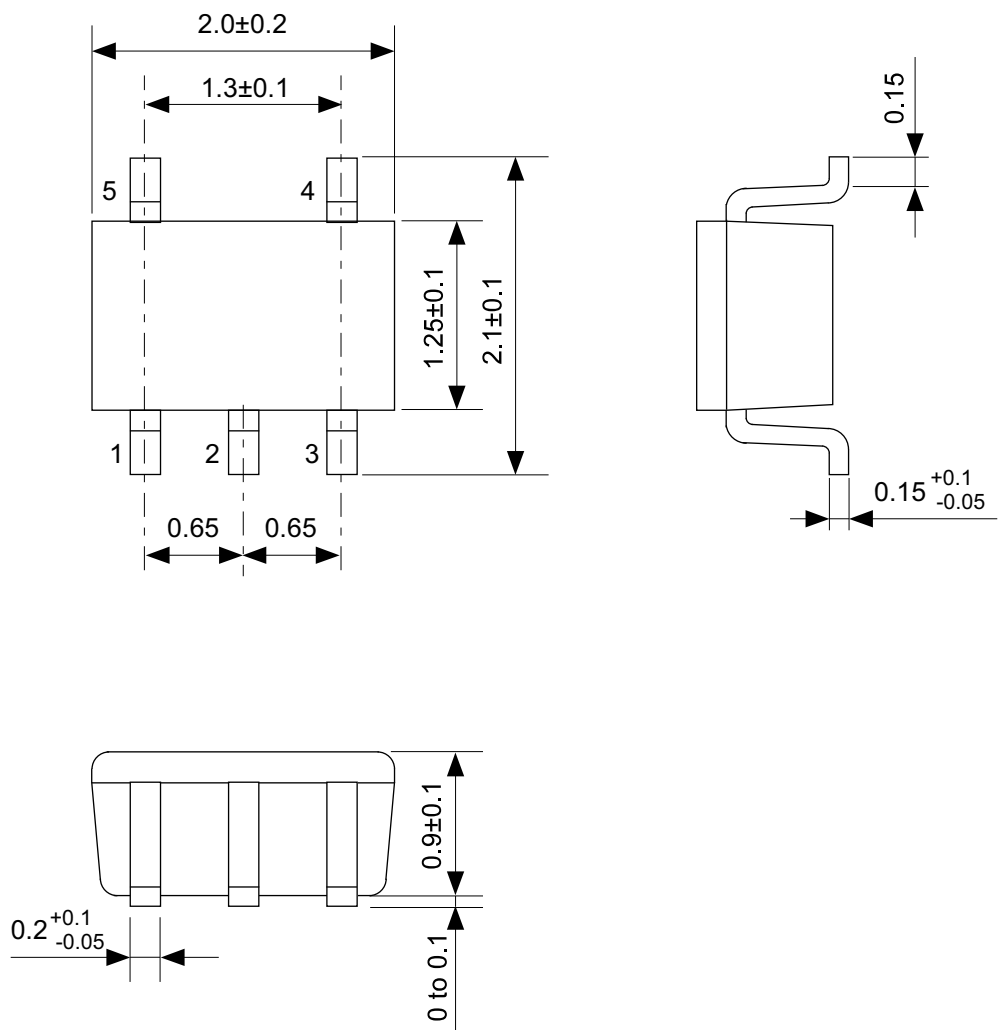


3.4 Output voltage (V_{OUT}) vs. I_{SINK}




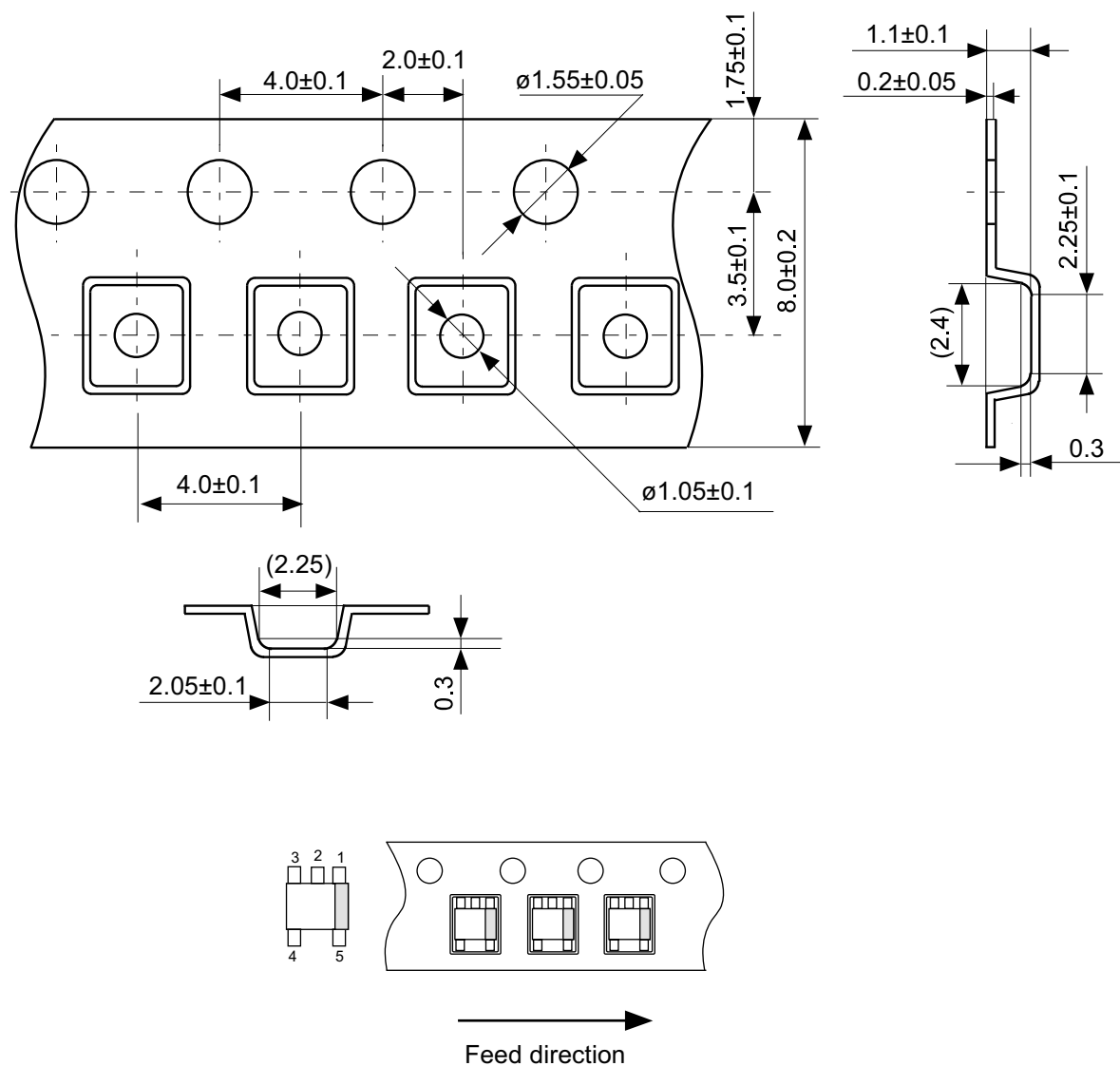
4. Current consumption (per circuit) vs. Common-mode input voltage range (voltage follower configuration)





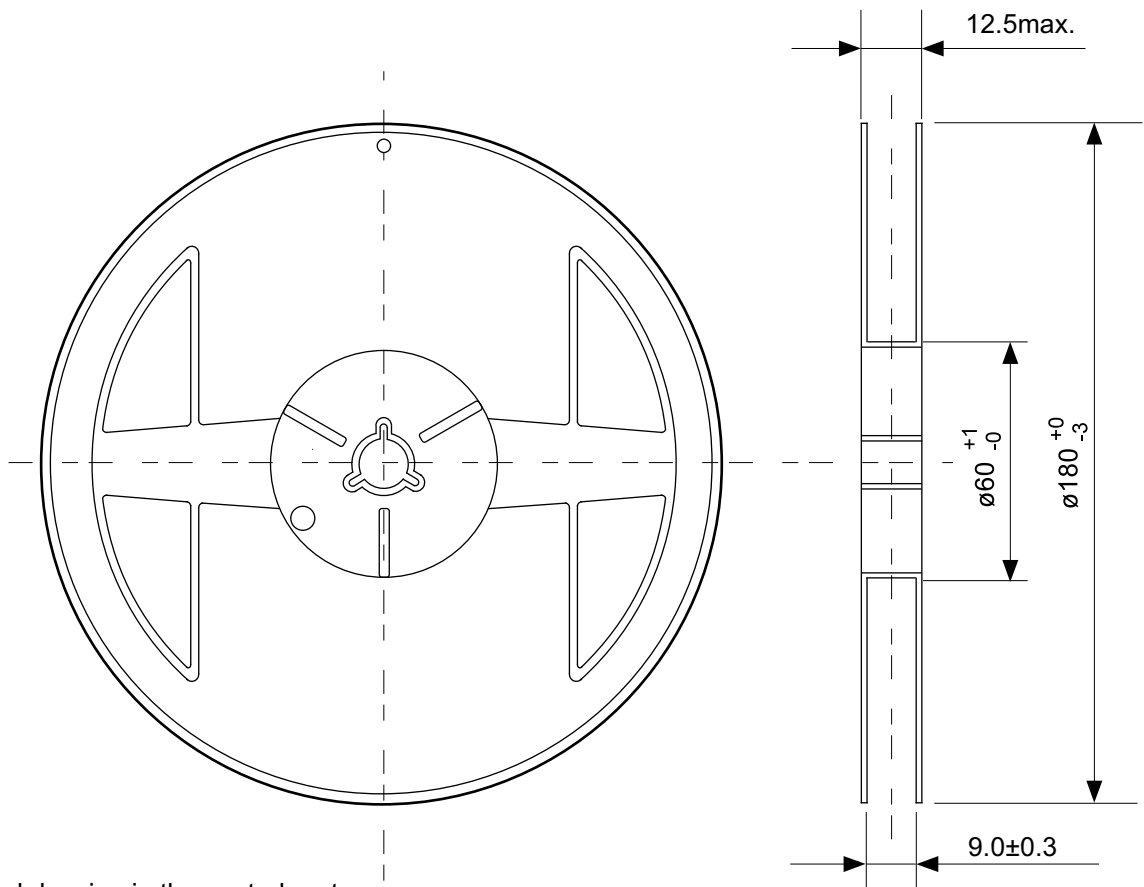
No. NP005-B-P-SD-1.2

TITLE	SC88A-B-PKG Dimensions
No.	NP005-B-P-SD-1.2
ANGLE	
UNIT	mm
ABLIC Inc.	

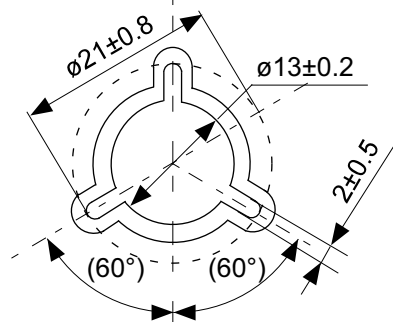


No. NP005-B-C-SD-2.0

TITLE	SC88A-B-Carrier Tape
No.	NP005-B-C-SD-2.0
ANGLE	
UNIT	mm
ABLIC Inc.	

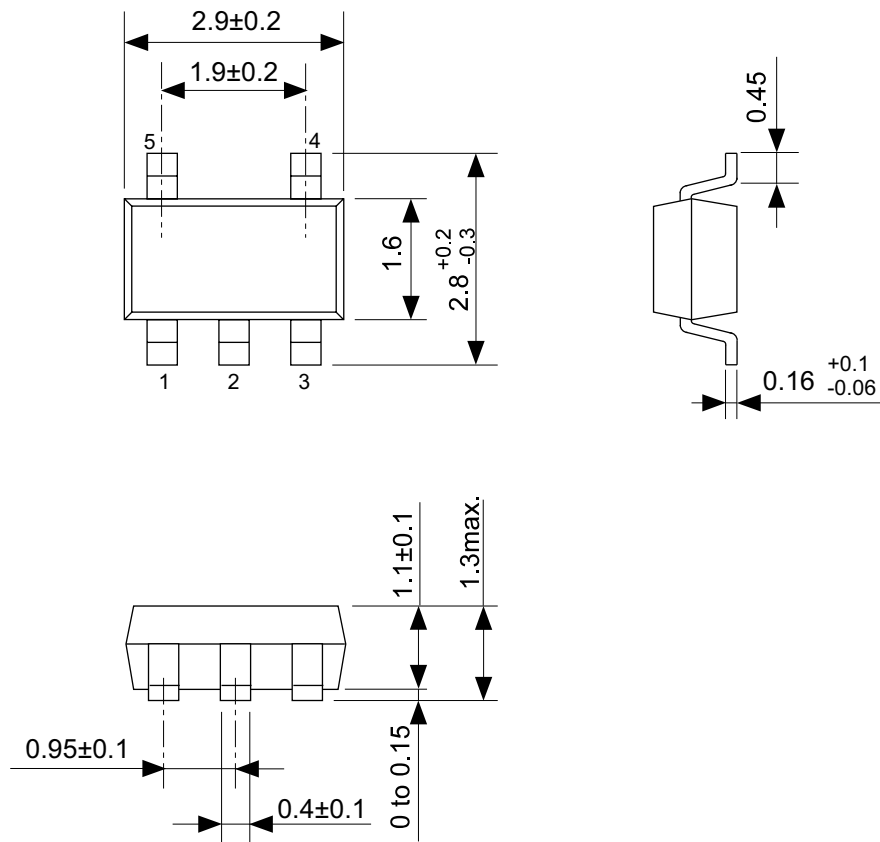


Enlarged drawing in the central part




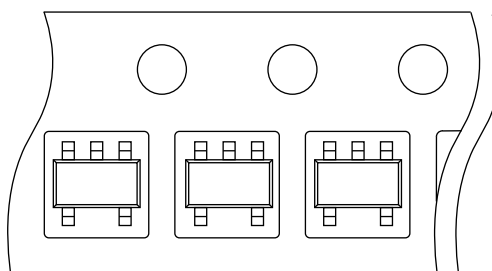
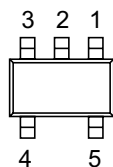
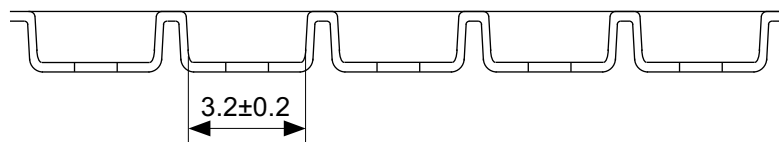
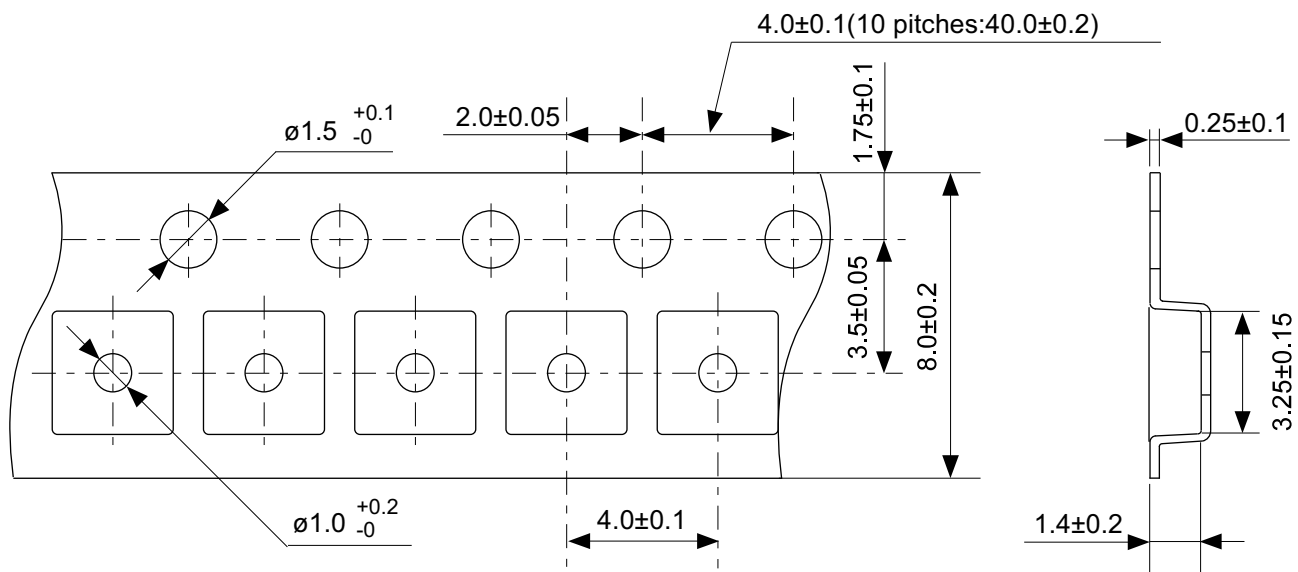
No. NP005-B-R-SD-2.1

TITLE	SC88A-B-Reel		
No.	NP005-B-R-SD-2.1		
ANGLE		QTY.	3,000
UNIT	mm		
ABLIC Inc.			



No. MP005-A-P-SD-1.3

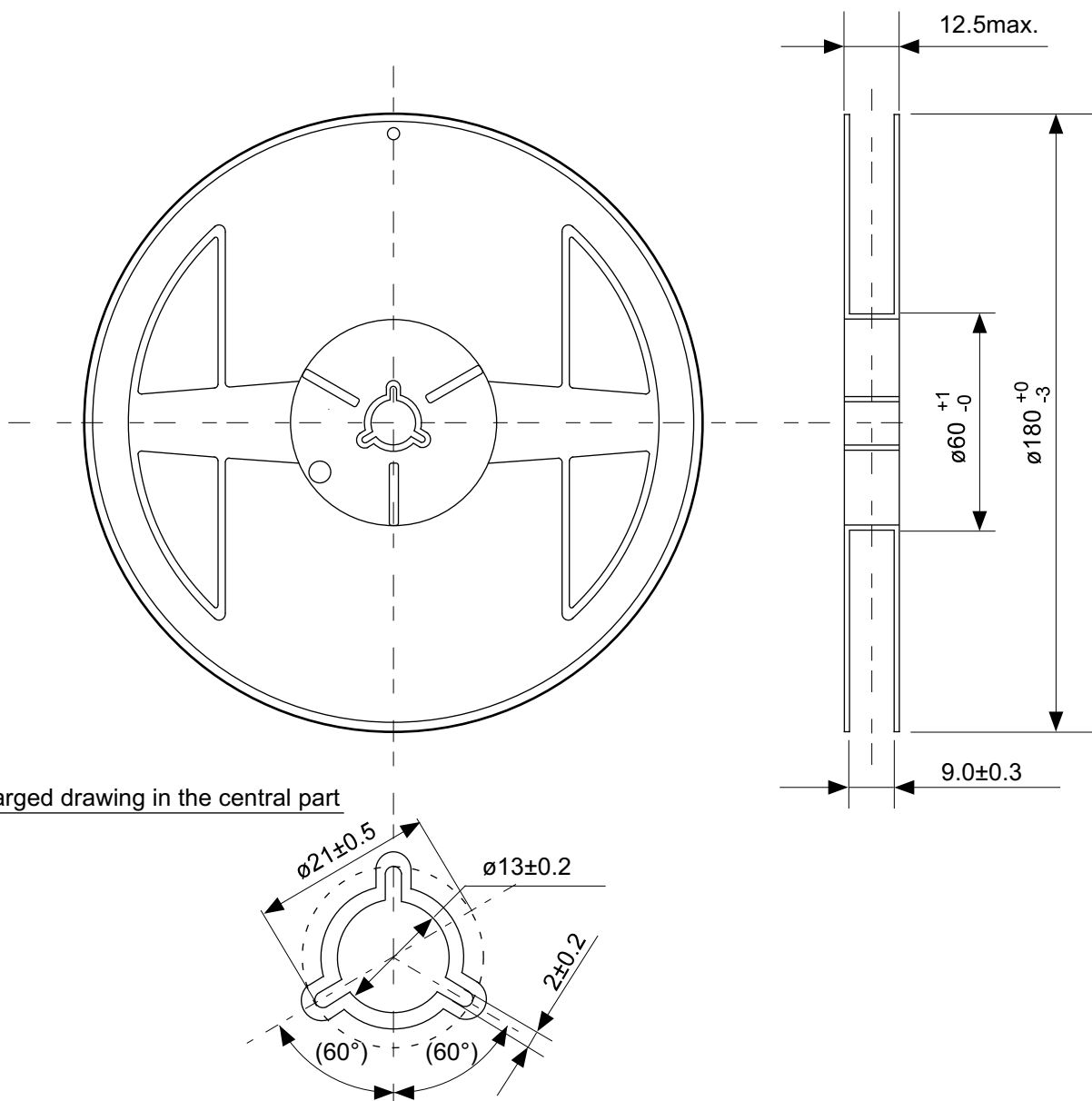
TITLE	SOT235-A-PKG Dimensions
No.	MP005-A-P-SD-1.3
ANGLE	
UNIT	mm
ABLIC Inc.	



Feed direction

No. MP005-A-C-SD-2.1

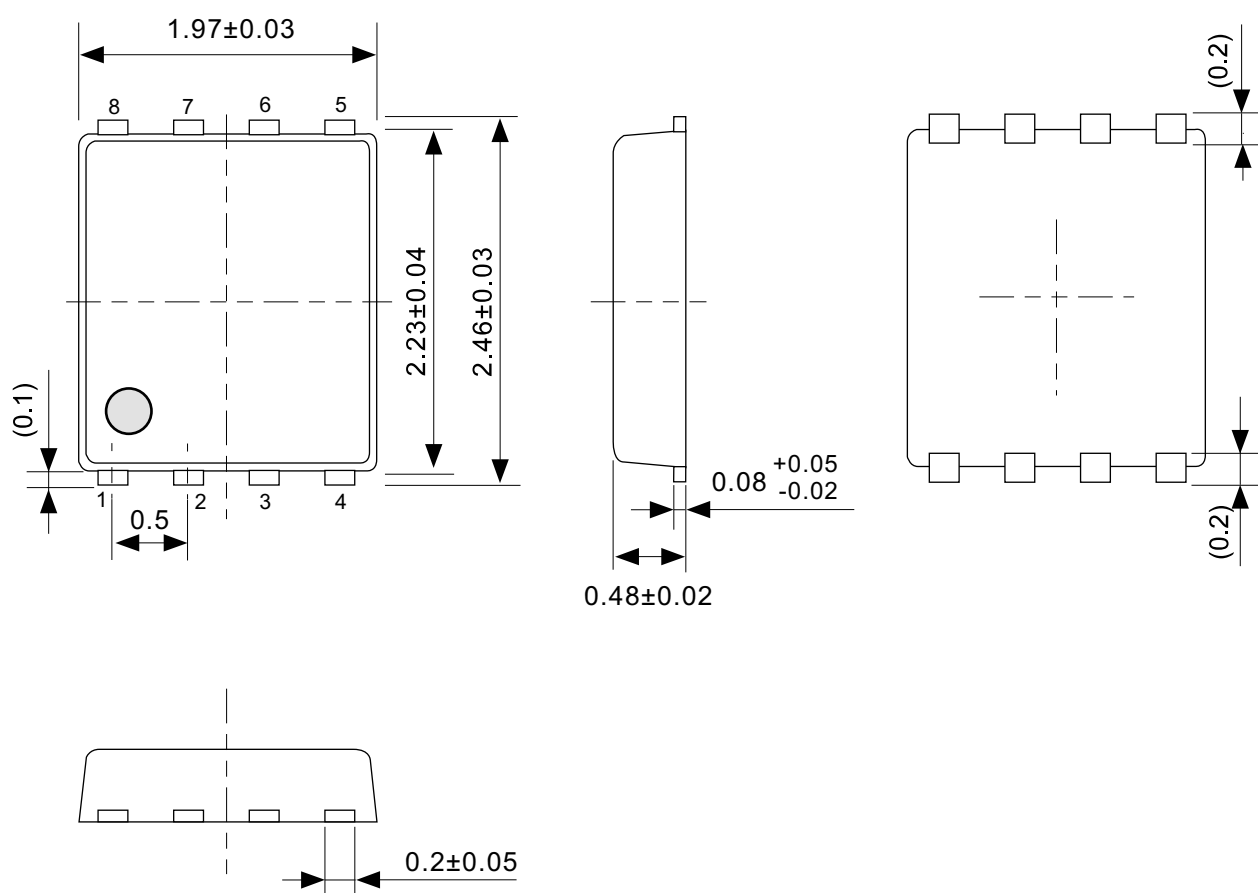
TITLE	SOT235-A-Carrier Tape
No.	MP005-A-C-SD-2.1
ANGLE	
UNIT	mm
ABLIC Inc.	




Enlarged drawing in the central part

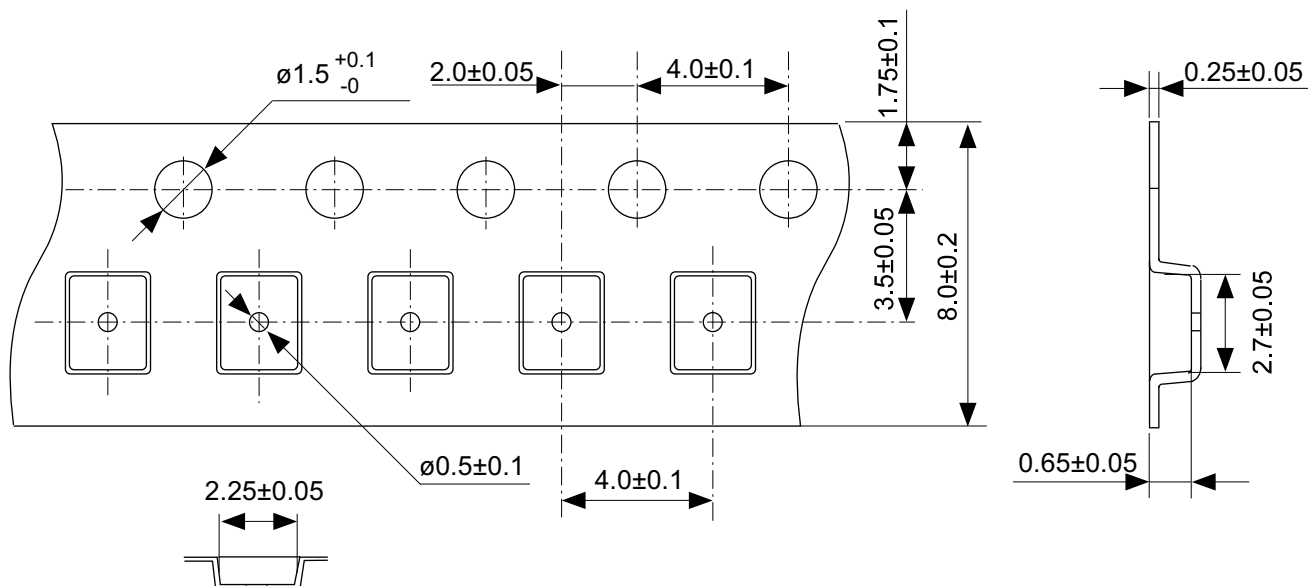
No. MP005-A-R-SD-1.1

TITLE	SOT235-A-Reel		
No.	MP005-A-R-SD-1.1		
ANGLE		QTY.	3,000
UNIT	mm		
ABLIC Inc.			

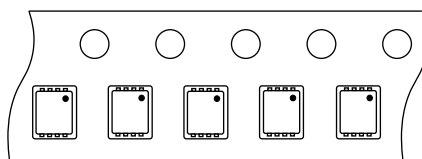


No. PH008-A-P-SD-2.1

TITLE	SNT-8A-A-PKG Dimensions
No.	PH008-A-P-SD-2.1
ANGLE	
UNIT	mm
ABLIC Inc.	



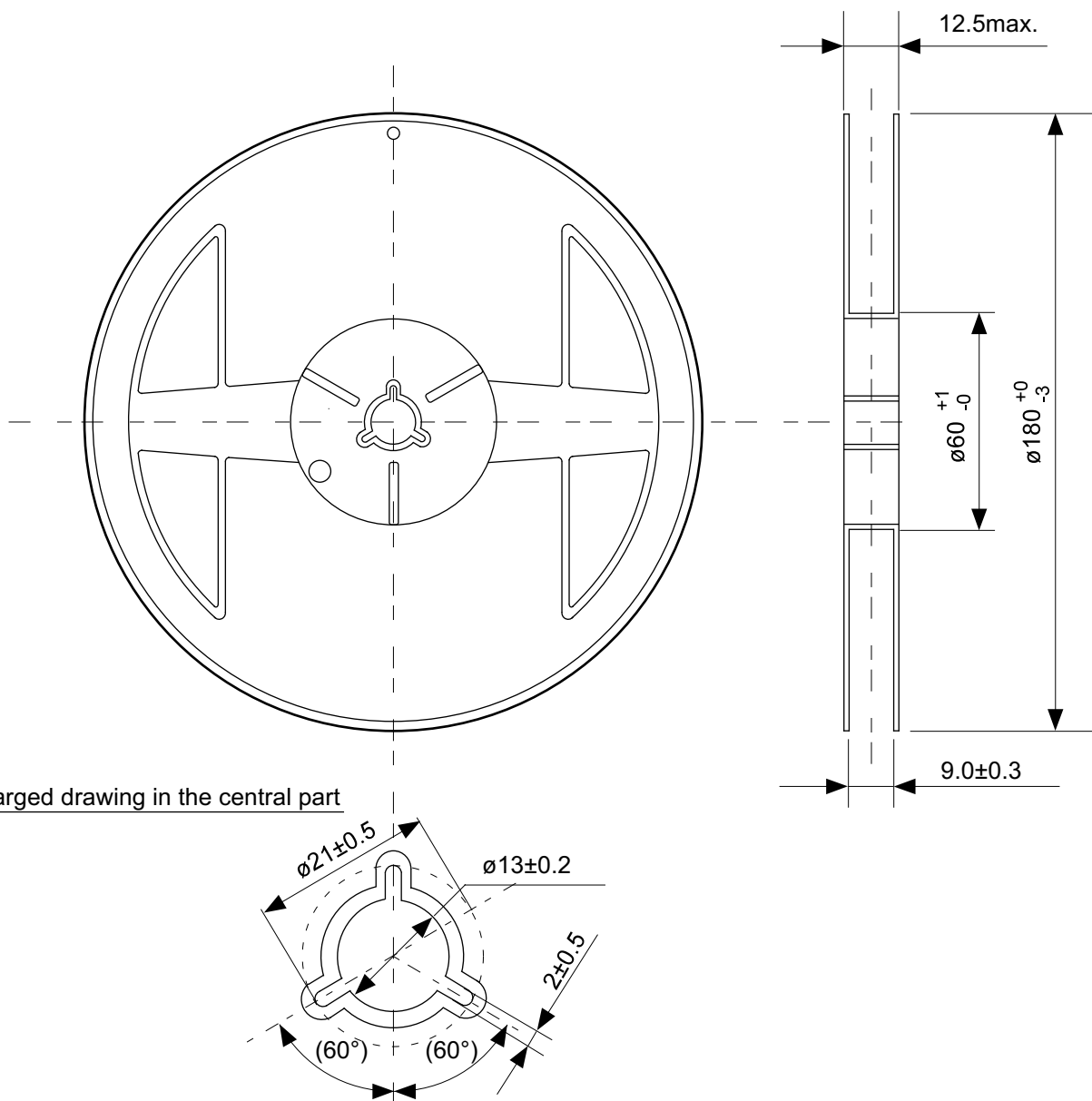
4 3 2 1
5 6 7 8



Feed direction

No. PH008-A-C-SD-2.0

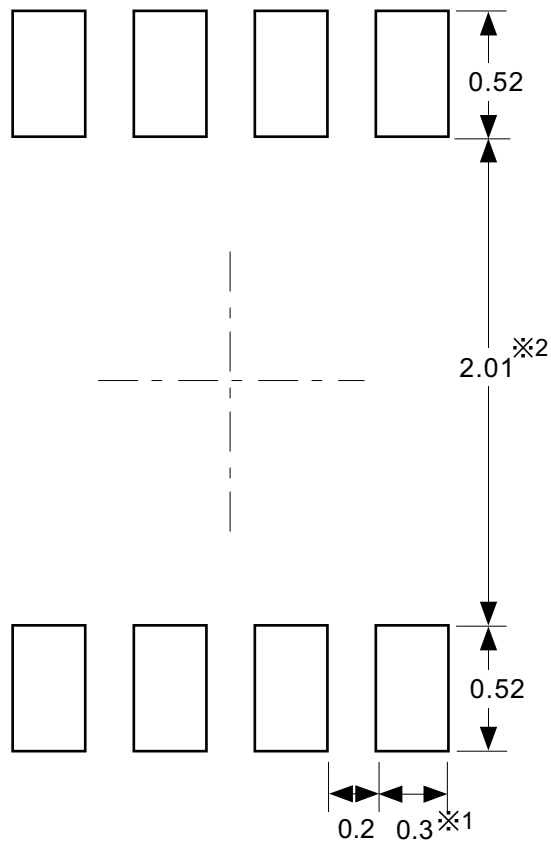
TITLE	SNT-8A-A-Carrier Tape
No.	PH008-A-C-SD-2.0
ANGLE	
UNIT	mm
ABLIC Inc.	



Enlarged drawing in the central part

No. PH008-A-R-SD-1.0

TITLE	SNT-8A-A-Reel		
No.	PH008-A-R-SD-1.0		
ANGLE		QTY.	5,000
UNIT	mm		
ABLIC Inc.			



※1. ランドパターンの幅に注意してください (0.25 mm min. / 0.30 mm typ.).
 ※2. パッケージ中央にランドパターンを広げないでください (1.96 mm ~ 2.06 mm)。

- 注意
1. パッケージのモールド樹脂下にシルク印刷やハンダ印刷などしないでください。
 2. パッケージ下の配線上のソルダーレジストなどの厚みをランドパターン表面から0.03 mm以下にしてください。
 3. マスク開口サイズと開口位置はランドパターンと合わせてください。
 4. 詳細は "SNTパッケージ活用の手引き" を参照してください。

※1. Pay attention to the land pattern width (0.25 mm min. / 0.30 mm typ.).
 ※2. Do not widen the land pattern to the center of the package (1.96 mm to 2.06mm).

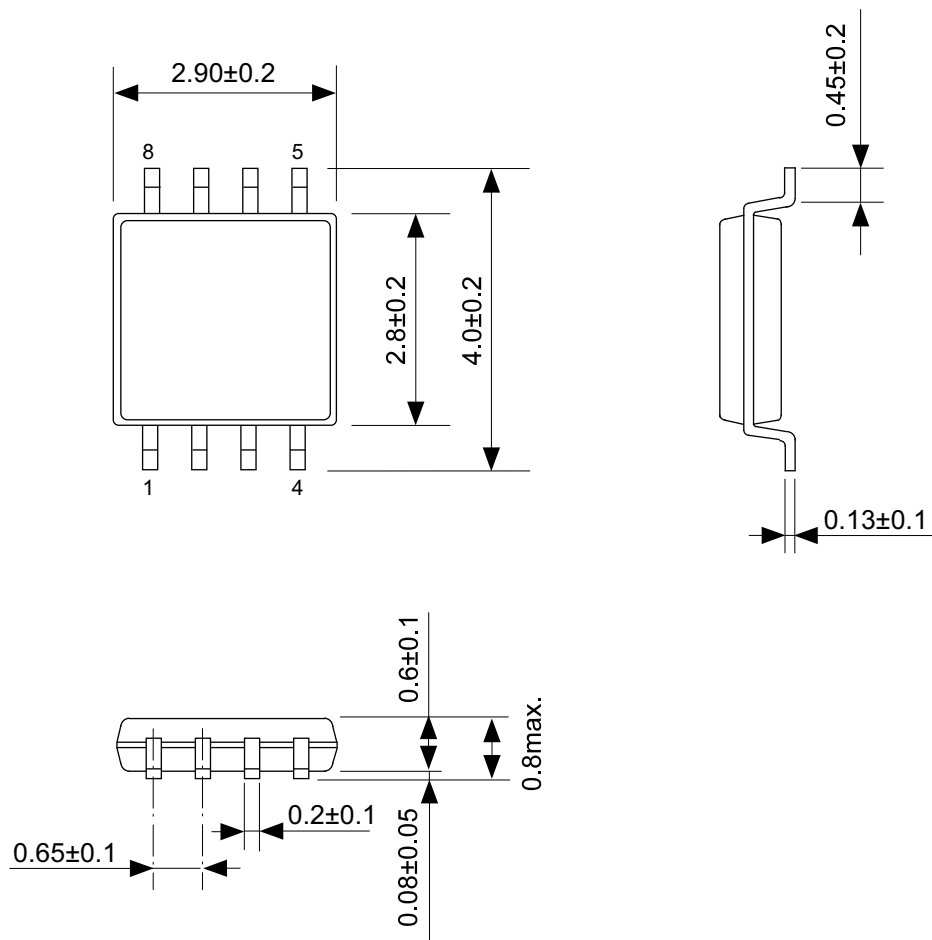
- Caution**
1. Do not do silkscreen printing and solder printing under the mold resin of the package.
 2. The thickness of the solder resist on the wire pattern under the package should be 0.03 mm or less from the land pattern surface.
 3. Match the mask aperture size and aperture position with the land pattern.
 4. Refer to "SNT Package User's Guide" for details.

※1. 请注意焊盘模式的宽度 (0.25 mm min. / 0.30 mm typ.).
 ※2. 请勿向封装中间扩展焊盘模式 (1.96 mm ~ 2.06 mm)。


- 注意
1. 请勿在树脂型封装的下面印刷丝网、焊锡。
 2. 在封装下、布线上的阻焊膜厚度 (从焊盘模式表面起) 请控制在 0.03 mm 以下。
 3. 钢网的开口尺寸和开口位置请与焊盘模式对齐。
 4. 详细内容请参阅 "SNT 封装的应用指南"。

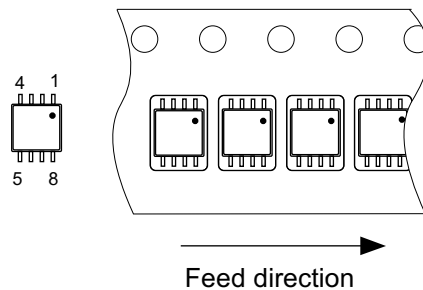
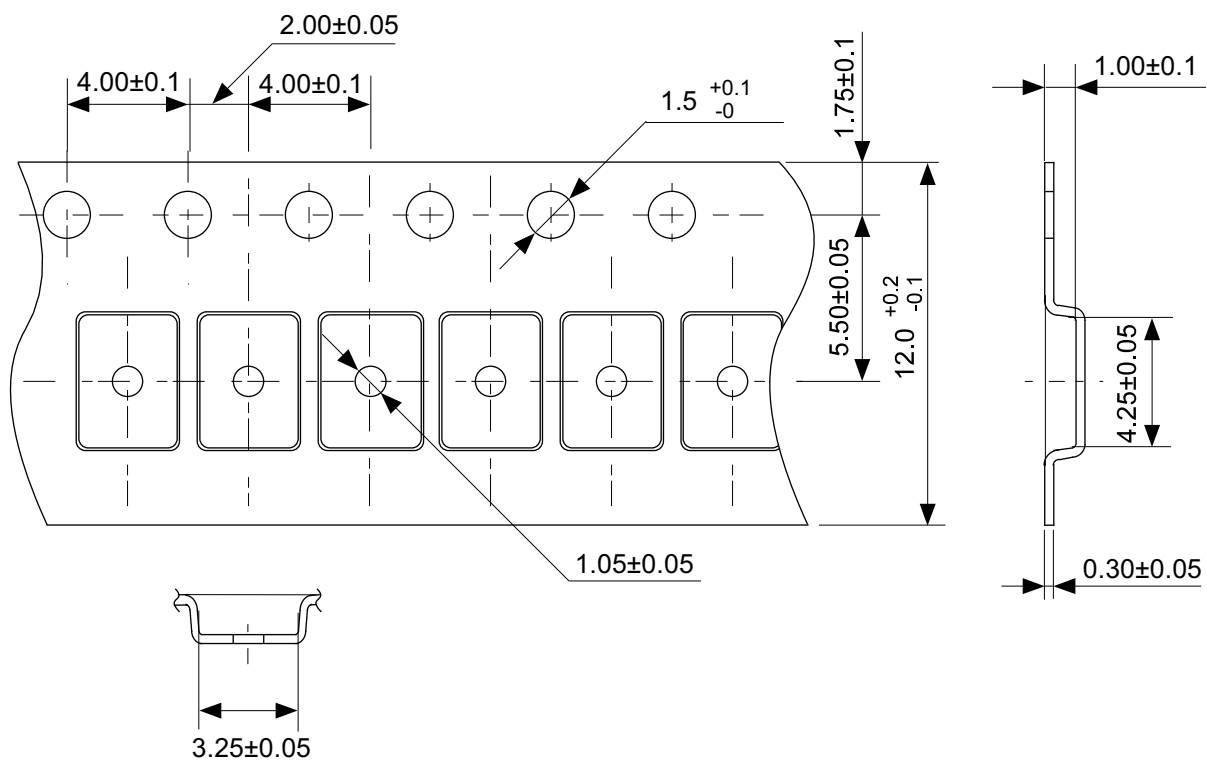
No. PH008-A-L-SD-4.1

TITLE	SNT-8A-A -Land Recommendation
No.	PH008-A-L-SD-4.1
ANGLE	
UNIT	mm
ABLIC Inc.	



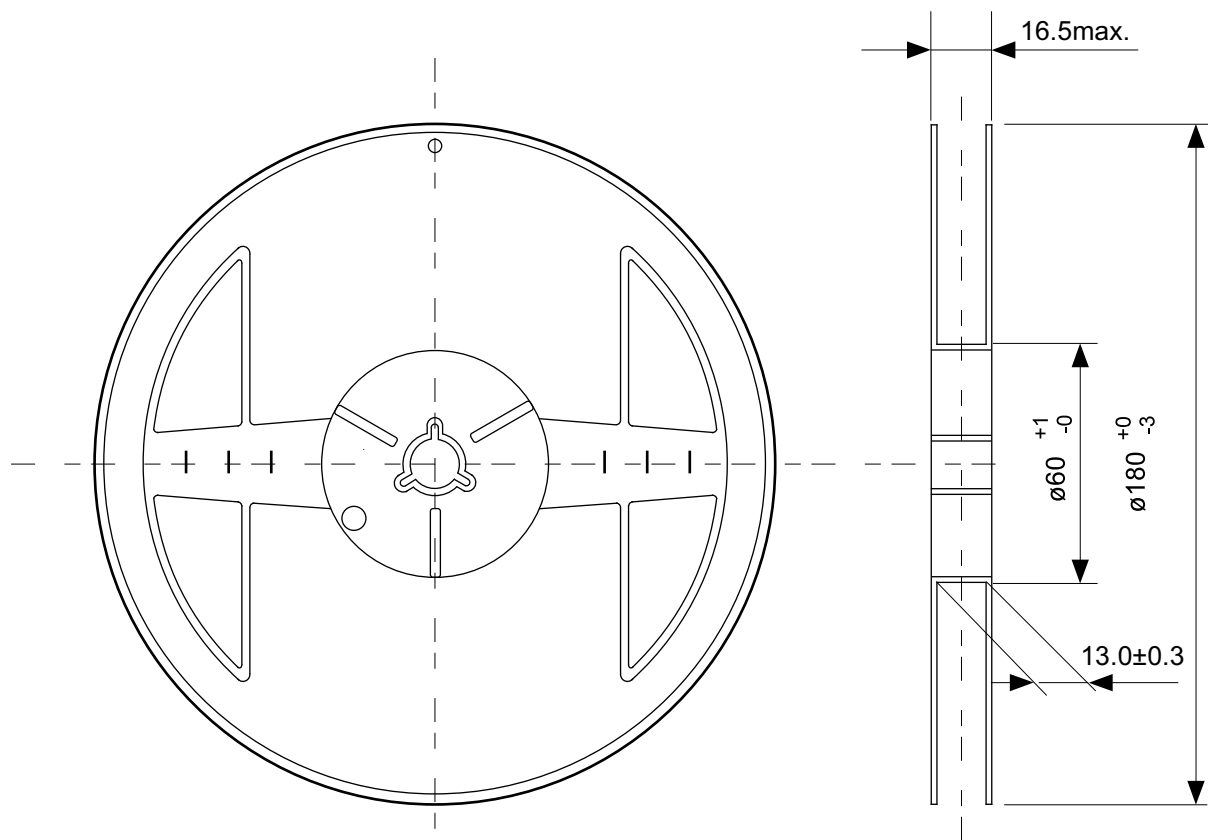
No. FM008-A-P-SD-1.2

TITLE	TMSOP8-A-PKG Dimensions
No.	FM008-A-P-SD-1.2
ANGLE	
UNIT	mm
ABLIC Inc.	

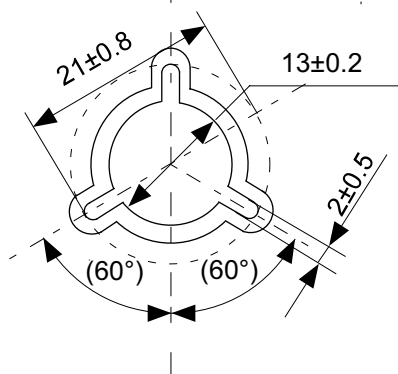


No. FM008-A-C-SD-2.0

TITLE	TMSOP8-A-Carrier Tape
No.	FM008-A-C-SD-2.0
ANGLE	
UNIT	mm
ABLIC Inc.	



Enlarged drawing in the central part



No. FM008-A-R-SD-1.0

TITLE	TMSOP8-A-Reel		
No.	FM008-A-R-SD-1.0		
ANGLE		QTY.	4,000
UNIT	mm		
ABLIC Inc.			

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2.4-2019.07